INTEGRATED CIRCUITS



Product specification

1999 Sep 13



GTL16612

FEATURES

- 18-bit bidirectional bus interface
- Translates between GTL/GTL+ logic levels (B ports) and LVTTL/TTL logic levels (A ports)
- 5 V I/O tolerant on the LVTTL/TTL side (A ports)
- No bus current loading when LVTTL/TTL output is tied to 5 V bus
- 3-State buffers
- Output capability: +64 mA/-32 mA on the LVTTL/TTL side (A ports); +40 mA on the GTL side (B ports)
- TTL input levels on control pins
- Power-up reset
- Power-up 3-State
- Positive edge triggered clock inputs
- Latch-up protection exceeds 500 mA per JESD78
- ESD protection exceeds 2000 V HBM per JESD22-A114, 200 V MM per JESD22-A115 and 1000 V CDM per JESD22-C101

QUICK REFERENCE DATA

DESCRIPTION

The GTL16612 is a high-performance BiCMOS product designed for V_{CC} operation at 3.3 V with I/O compatibility up to 5 V.

This device is an 18-bit universal transceiver featuring non-inverting 3-State bus compatible outputs in both send and receive directions. Data flow in each direction is controlled by output enable (OEAB and OEBA), latch enable (LEAB and LEBA), and clock (CPAB and CPBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is High. When LEAB is Low, the A data is latched if CPAB is held at a High or Low logic level. If LEAB is Low, the A-bus data is stored in the latch/flip-flop on the Low-to-High transition of CPAB. When OEAB is Low, the outputs are active. When OEAB is High, the outputs are in the high-impedance state. The clocks can be controlled with the clock-enable inputs (CEBA/CEAB).

Data flow for B-to-A is similar to that of A-to-B but uses $\overline{\text{OEBA}},$ LEBA and CPBA.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
STWBOL	STMBOL PARAMETER $T_{amb} = 25^{\circ}C$		3.3 V	UNIT
t _{PLH} t _{PHL}	Propagation delay An to Bn or Bn to An	C _L = 50 pF	1.9	ns
C _{IN}	Input capacitance (Control pins)	$V_{I} = 0 V \text{ or } V_{CC}$	4	pF
C _{I/O}	I/O pin capacitance	Outputs disabled; $V_{I/O} = 0 V \text{ or } V_{CC}$	8	pF
I _{CCZ}	Total supply current	Outputs disabled	12	mA

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	ORDER CODE	DWG NUMBER
56-Pin Plastic TSSOP Type II	–40°C to +85°C	GTL16612 DGG	SOT364-1

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PIN CONFIGURATION



PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1, 27	OEAB/OEBA	A-to-B/ B-to-A Output enable input (active Low)
29, 56	CEBA/CEAB	B-to-A/A-to-B clock enable
2, 28	LEAB/LEBA	A-to-B/B-to-A Latch enable input
55,30	CPAB/CPBA	A-to-B/B-to-A Clock input (active rising edge)
3, 5, 6, 8, 9, 10, 12, 13, 14, 15, 16, 17, 19, 20, 21, 23, 24, 26	A0-A17	Data inputs/outputs (A side)
54, 52, 51, 49, 48, 47, 45, 44, 43, 42, 41, 40, 38, 37, 36, 34, 33, 31	B0-B17	Data inputs/outputs (B side)
4, 11, 18, 25, 32, 39, 46, 53	GND	Ground (0 V)
7, 22	V _{CC}	Positive supply voltage
35	V _{REF}	GTL reference voltage
50	NC	No connection

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LOGIC SYMBOL (Positive Logic)



FUNCTION TABLE

	INPUTS							
CEAB ¹	OEAB ¹	LEAB ¹	CPAB ¹	Α	В			
Х	Н	Х	Х	Х	Z			
Х	L	Н	Х	L	L			
Х	L	Н	Х	Н	Н			
Н	L	L	Х	Х	₿ ₀ ²			
Н	L	L	Х	Х	B _O ²			
L	L	L	\uparrow	L	L			
L	L	L	\uparrow	Н	Н			
L	L	L	Н	Х	B _O ²			
L	L	L	L	Х	B _O ² B _O ³			

X = Don't care

H = High voltage level

L = Low voltage level

 \uparrow = Low to High

Z = High impedance "off" state

1. A-to-B data flow is shown: B-to-A flow is similar but uses OEBA, LEBA, CPBA, and CEBA.

Output level before the indicated steady-state input conditions were established.
Output level before the indicated steady-state input conditions were established, provided that CPAB was Low before LEAB went Low.

ABSOLUTE MAXIMUM RATINGS 1, 2

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +4.6	V
I _{IK}	DC input diode current	V ₁ < 0	-50	mA
M		A port	-0.5 to +7.0	v
VI	DC input voltage ³	B port	-0.5 to +4.6	v
I _{OK}	DC output diode current	V _O < 0; A port	-50	mA
M		Output in Off or High state; A port	-0.5 to +7.0	V
Vo	DC output voltage ³	Output in Off or High state; B port	-0.5 to +4.6	V
		A port	128	mA
IOL	Current into any output in the LOW state	B port	80	mA
I _{OH}	Current into any output in the HIGH state	A port	-64	mA
T _{stg}	Storage temperature range		-65 to +150	°C

NOTES:

 Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
The input and output acception uptage up to a super the average of it to input and output to acception up to a super temperature.

3. The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

CYMDOL	DADAMETED	TEST CONDITIONS	3.3 V RAN	3.3 V RANGE LIMITS		
SYMBOL	PARAMETER	TEST CONDITIONS	MIN	MAX		
V _{CC}	DC supply voltage		3.0	3.6	V	
M	Termination voltage	GTL	1.14	1.26	v	
V _{TT}	Termination voltage	GTL+	1.35	1.65	1 ~	
M		GTL	0.74	0.87	v	
V _{REF}	GTL reference voltage	GTL+	0.9	1.10	1 ~	
N		B port	0	V _{TT}	v	
VI	Input voltage	Except B port	0	5.5	1 ~	
N		B port	V _{REF} +50 mV		v	
V _{IH}	HIGH-level input voltage	Except B port	2.0		1 ×	
V		B port		V _{REF} –50 mV	v	
V _{IL}	LOW-level input voltage	Except A port		0.8	1 ~	
I _{ОН}	HIGH-level output current	A port		-32	mA	
		B port		40		
I _{OL}	LOW-level output current	A port		64	mA	
T _{amb}	Operating free-air temperature range		-40	+85	°C	

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DC ELECTRICAL CHARACTERISTICS (3.3 V ±0.3 V RANGE)

						LIMITS		
SYMBOL	PARAM	METER	TEST CONDITIONS		Temp = -	UNIT		
					MIN	TYP ¹	MAX	
VIK	Input clamp vo	ltage	V _{CC} = 3.0 V; I _{IK} = -18 mA			-0.85	-1.2	V
N/	Link laurel auto		V_{CC} = 3.0 to 3.6 V; I_{OH} = –100 μA	A nort	V _{CC} -0.2	V _{CC}		v
V _{OH}	High-level outp	out voltage	V _{CC} = 3.0 V; I _{OH} = -32 mA	A port	2.0	2.3		
			$V_{CC} = 3.0 \text{ V}; I_{OL} = 100 \ \mu\text{A}$			0.07	0.2	
			V _{CC} = 3.0 V; I _{OL} = 16 mA	1 A north		0.25	0.4	
V _{OL}	Low-level outp	out voltage	V _{CC} = 3.0 V; I _{OL} = 32 mA	A port		0.3	0.5	V
			V _{CC} = 3.0 V; I _{OL} = 64 mA	1		0.4	0.55	
			V _{CC} = 3.0 V; I _{OL} = 40 mA	B port		0.4	0.5	V
			V_{CC} = 3.6 V; V_{I} = V_{CC} or GND	Control size		0.1	±1	μA
			$V_{CC} = 0 \text{ or } 3.6 \text{ V}; \text{ V}_{I} = 5.5 \text{ V}$	Control pins		0.1	10	
			V _{CC} = 3.6 V; V _I = 5.5 V	_		0.1	20	
ł _i	Input leakage current	current	$V_{CC} = 3.6 \text{ V}; \text{ V}_{I} = V_{CC}$	I/O Data pins ⁴ A port		0.5	10	μA
			$V_{CC} = 3.6 \text{ V}; \text{ V}_{I} = 0$			0.1	-5	
			V_{CC} = 3.6 V; V_{I} = V_{TT} or GND	B port			±5	μA
I _{OFF}	Output off curre	ent	V_{CC} = 0 V; V_{I} or V_{O} = 0 to 4.5 V			0.1	±100	μA
	Due Held ourse		$V_{CC} = 3 \text{ V}; \text{ V}_{I} = 0.8 \text{ V}$			130		
HOLD	Bus Hold curre	ini, A outputs	$V_{CC} = 3 \text{ V}; \text{ V}_{I} = 2.0 \text{ V}$	-75	-140		μA	
I_{EX}	Current into an High state whe		$V_{O} = 5.5 \text{ V}; V_{CC} = 3.0 \text{ V}$	A port		10	125	μΑ
I _{PU/PD}	Power up/dowr output current ³		$V_{CC} \leq$ 1.2 V; V_{O} = 0.5 V to $V_{CC};$ V \overline{OE} = Don't care	$V_{I} = GND \text{ or } V_{CC}$		1.0	±100	μA
I _{CCH}			Outputs high			5.0	9.0	
I _{CCL}	A-Port		Outputs low	1		10.5	18.5	1
I _{CCZ} 5		V _{CC} = 3.6 V	Disabled	$V_{I} = GND \text{ or } V_{CC}, I_{O} = 0$		6.0	11.5	mA
I _{CCH}	D Dort		Outputs high	1		9.7	17.5	
I _{CCL}	B-Port		Outputs low	1		7.0	12.0	
ΔI_{CC}	Additional supp input pin ²	bly current per	V_{CC} = 3 V to 3.6 V; One input at V Other inputs at V _{CC} or GND	, _{CC} –0.6 V,		0.04	0.2	mA

NOTES:

1. All typical values are at $V_{CC} = 3.3 \text{ V}$ and $T_{amb} = 25^{\circ}\text{C}$. 2. This is the increase in supply current for each LVTTL input at the specified voltage level other than V_{CC} or GND 3. This parameter is valid for any V_{CC} between 0 V and 1.2 V with a transition time of up to 10 msec. From $V_{CC} = 1.2 \text{ V}$ to $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ a transition time of 100 µsec is permitted. This parameter is valid for $T_{amb} = 25^{\circ}\text{C}$ only.

4. Unused pins at V_{CC} or GND.

5. I_{CCZ} is measured with outputs pulled up to V_{CC} or pulled down to ground.

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AC CHARACTERISTICS (A PORT)

GND = 0 V; t_r = t_f = 2.5 ns; C_L = 50 pF; R_L = 500 Ω ; T_{amb} = -40°C to +85°C.

				GTL			GTL+		
	GTL16612 An Po	ort	V _{CC} = 3.3 V ±0.3 V			Vcc	1		
			, I	V _{REF} = 0.8 \	/	,	V _{REF} = 1.0 \	/	UNIT
SYMBOL	PARAMETER	WAVEFORM	MIN	TYP ¹	MAX	MIN	TYP ¹	MAX	
t _{PLH}	Bn to An	2	1.6	3.0	5.0	1.6	3.0	5.0	ns
t _{PHL}	Bn to An	2	3.0	4.9	6.3	3.0	4.9	6.3	ns
t _{PLH}	LEBA to An	3	1.6	2.7	4.2	1.6	2.7	4.2	ns
t _{PHL}	LEBA to An	3	1.6	2.8	4.3	1.6	2.8	4.3	ns
t _{PLH}	CPBA to An	1	1.9	3.4	4.7	1.9	3.4	4.7	ns
t _{PHL}	CPBA to An	1	1.8	3.8	5.2	1.8	3.8	5.2	ns
t _{PZH}	OEBA to An	5	1.5	2.6	4.2	1.5	2.6	4.2	ns
t _{PHZ}	OEBA to An	5	1.4	2.9	4.8	1.4	2.9	4.8	ns
t _{PZL}	OEBA to An	6	1.3	2.4	3.8	1.3	2.4	3.8	ns
t _{PLZ}	OEBA to An	6	1.2	2.2	3.5	1.2	2.2	3.5	ns

NOTE:

1. Typical values are at V_{CC} = 3.3 V, T_{amb} = +25°C.

AC CHARACTERISTICS (B PORT)

GND = 0 V; $t_r = t_f = 2.5 \text{ ns}$; $C_L = 30 \text{ pF}$; $R_L = 25 \Omega$; $T_{amb} = -40^{\circ}\text{C}$ to +85°C.

				GTL			GTL+		
	GTL16612 Bn Po	rt	V _{CO}	_c = 3.3 V ±0.	3 V	Vcc	; = 3.3 V ±0.	.3 V	
				V _{REF} = 0.8 V			V _{REF} = 1.0 V		
SYMBOL	PARAMETER	WAVEFORM	MIN	TYP ¹	MAX	MIN	TYP ¹	MAX	
t _{PLH}	An to Bn	2	1.4	2.4	3.7	1.3	2.4	3.7	ns
t _{PHL}	An to Bn	2	1.3	2.5	4.0	1.4	2.6	4.2	ns
t _{PLH}	LEAB to Bn	3	1.7	3.0	4.4	1.8	3.0	4.6	ns
t _{PHL}	LEAB to Bn	3	2.1	3.5	5.4	2.3	3.6	5.5	ns
t _{PLH}	CPAB to Bn	1	1.8	3.1	4.5	1.9	3.1	4.8	ns
t _{PHL}	CPAB to Bn	1	2.3	3.6	5.4	2.4	3.8	5.8	ns
t _{PLH}	OEAB to Bn	7	1.1	2.1	3.3	1.4	2.0	3.5	ns
t _{PHL}	OEAB to Bn	7	1.6	2.8	4.4	1.0	2.9	4.5	ns

NOTE:

1. Typical values are at V_{CC} = 3.3 V, T_{amb} = +25°C.

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AC SETUP REQUIREMENTS (3.3 V ±0.3 V RANGE)

A Port: GND = 0 V; Input $t_r = t_f = 2.5 \text{ ns}$; $C_L = 50 \text{ pF}$; $R_L = 500 \Omega$; $T_{amb} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$; $V_{REF} = 0.8 \text{ V or } 1.0 \text{ V}$. B Port: GND = 0 V; Input $t_r = t_f = 2.5 \text{ ns}$; $C_L = 30 \text{ pF}$; $R_L = 25 \Omega$; $V_{REF} = 0.8 \text{ V or } 1.0 \text{ V}$.

			LIN	UNIT	
SYMBOL	PARAMETER	WAVEFORM	V_{CC} = 3.3 V ±0.3 V		
			MIN	MAX	1
t _s (H)	Setup time, High or Low	4	1.5		ns
t _s (L)	Bn to CPBA	4	1.5		ns
t _s (H)	Setup time, High or Low	4	2.0		ns
t _s (L)	An to CPAB	4	3.0		ns
t _h (H)	Hold time, High or Low	4	1.0		ns
t _h (L)	Bn to CPBA, or An to CPAB	4	1.0		ns
t _s (H)	Setup time, High or Low	4	1.0		ns
t _s (L)	Bn to LEBA, or An to LEAB	4	1.0		ns
t _h (H)	Hold time, High or Low	4	1.5		ns
t _h (L)	Bn to LEBA, or An to LEAB	4	1.5		ns
t _s (H)	Setup time, High or Low	4	1.0		ns
t _s (L)	CEAB to CPAB, or CEBA to CPBA	4	1.0		ns
t _h (H)	Hold time, High or Low	4	1.5		ns
t _h (L)	CEAB to CPAB, or CEBA to CPBA	4	1.0		ns
t _w (H)	Pulse width, High or Low	4	2.0		ns
t _w (L)	CPBA or CPAB	4	2.0		ns
t _w (H)	Pulse width, High LEBA or LEAB	3	1.5		ns

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AC WAVEFORMS

 $V_M = 1.5 V$ at $V_{CC} \ge 3.0 V$. $V_M = 1.5 V$ for A ports and control pins; $V_M = 0.8 V$ for B ports in GTL mode; $V_M = 1.0 V$ for B ports in GTL+ mode. $V_X = V_{OL} + 0.3 V$ at $V_{CC} \ge 3.0 V$. $V_Y = V_{OH} - 0.3 V$ at $V_{CC} \ge 3.0 V$.



Waveform 1. Propagation delay, clock input to output, clock pulse width, and maximum clock frequency



Waveform 2. Propagation delay, transparent mode



Waveform 3. Propagation delay, enable to output, and enable pulse width



Waveform 4. Data setup and hold times



Waveform 5. 3-State output enable time to high level and output disable time from high level



Waveform 6. 3-State output enable time to low level and output disable time from low level



Waveform 7. Output enable time on open collector output with pullup

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TEST CIRCUIT



SW00255

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
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[1] Please consult the most recently issued datasheet before initiating or completing a design.

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Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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